

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5985	(semiconductor adj (chip or die)) and (through adj hole) and resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/05 10:31
L2	453	(semiconductor adj (chip or die)) and (through adj hole) and resin and (conductive adj pattern)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/05 10:52
L3	5187	(semiconductor adj (chip or die)) and (through adj hole) and resin and (plurality of electrodes)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/05 10:32
L4	759	(semiconductor adj (chip or die)) and (through adj hole) and resin and (inner adj leads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/05 10:33
L5	1905	(semiconductor adj (chip or die)) and (through adj hole) and resin and (insulating adj (film or layer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/05 10:34
L6	2	"5736780".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/05 10:52